

In the Specification:

Please amend the third paragraph beginning on page 3 as follows:

-- These and other objects are achieved by the present invention which comprises a photomask and a method of manufacturing a photomask which is protected against ESD (~~electrostatic discharge~~) or electrostatic damage. According to the invention ~~inventions~~, there is included a substrate such as fused quartz or silica which is transparent to the wavelength of light used for printing circuits or microchips on a wafer. The substrate includes a front face and a back face with a pattern permanently applied or adhered to the front face. The pattern is opaque to the wavelength of light used for printing and is typically a metal such as chromium and molybdenum silicide. A conductive film which is also transparent to light having a wavelength used for printing is deposited at least over those portions of the front face of the substrate not covered by the opaque pattern. For example, according to one embodiment, the conductive transparent film covers the entire front face including a previously deposited pattern. However, according to another embodiment, the conductive transparent film is deposited before the pattern is deposited and covers the entire front face. The pattern is then deposited over the combination substrate and conductive transparent film. The "transparent" conductive film is selected from a group of materials consisting of ITO (Indium Tin Oxide), Palladium, Platinum, Gold and conductive polymers, depending on the wavelength of the light chosen for printing. In addition, the thickness of the deposited layer of film will also be dependent upon the wavelength of the light used for printing.--

Please amend the first sentence on page 12 as follows:

--What is claimed is:--